

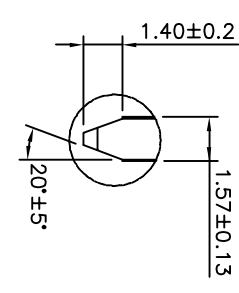
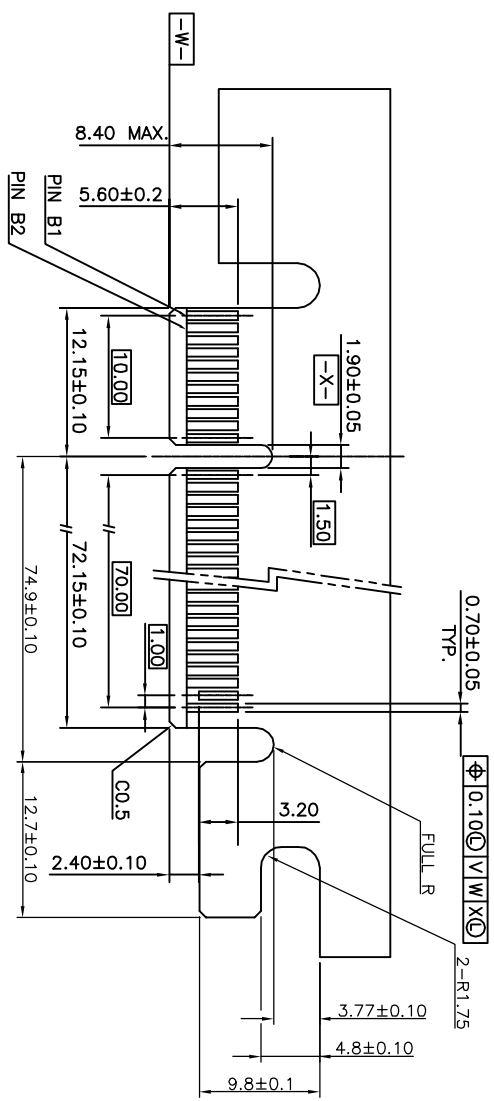
SEC A-A

SEC B-B
SECALE 2:1

mat'l. code		ecn no		dr		dtdt		tolerances unless otherwise specified		CUSTOMER COPY		FCI	
A	T05-0046	J.H	2/23/05	linear	.XX ± 0.25	projection	MM	product family	PCI-E INTEGRATED TYPE	code	TWN	product family	EDGE CARD
B	T05-0067	J.H	3/28/05	.XXX ± 0.10	0° ± 2°	scdle	1:1	size dwg no	10046742	code	1 of	product family	EDGE CARD
C	T05-0227	J.H	09/30/05	angles		chr	STERLING LN	2/23/05		sheet	1 of	product family	EDGE CARD
D	T06-0187	J.H	11/13/06	dr		pppd	HC LOU	2/23/05		sheet	1 of	product family	EDGE CARD
E	T07-1125	J.H	08/02/07	engr						sheet	1 of	product family	EDGE CARD
sheet		revision		1		E		2		E		3	
index		sheet		1		E		2		E		3	

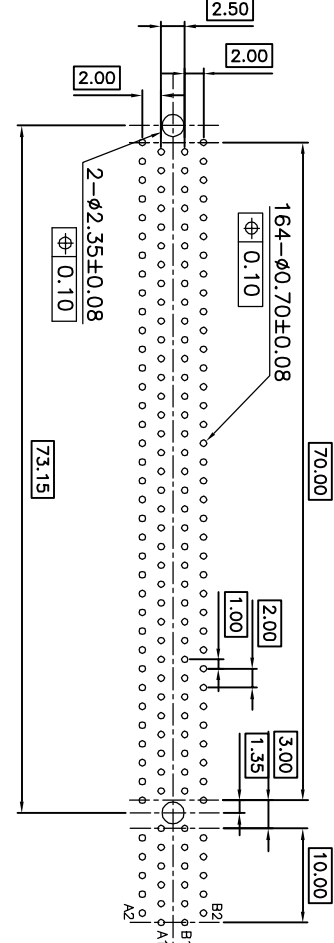
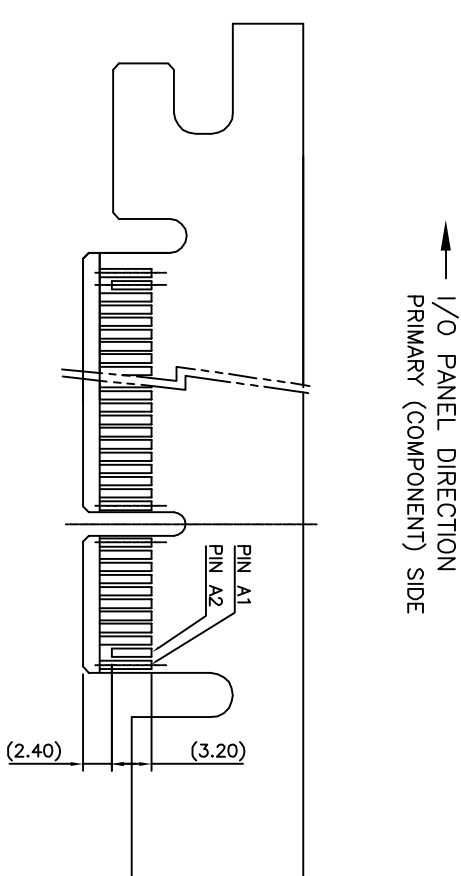
ACAD

page code
22526



SCALE 2:1

ADD-IN CARD EDGE-FINGER DIMENSIONS



RECOMMENDED FOOTPRINT LAYOUT

mod'l. code	tolerances unless otherwise specified		CUSTOMER COPY	FCI	title	product family	code
itr	ecn no	dr	date	linear	.XX ± 0.25	projection	www.fciconnect.com
E				angular	° ± 2°	MM	PCI-E INTEGRATED TYPE CARD EDGE ASS'Y
				dr	JASON HSU 2/23/05	scale	EDGE CARD
				engr	JASON HSU 2/23/05	1:1	product family
				chr	STERLING LIN 2/23/05	size	dwg no
				appd	HC LIU 2/23/05	A4	10046742
sheet	revision						code
index	sheet						TWN
							sheet
							2 of

1 | 2

ACAD

3 |

code code 22526

4



1 | 2

3

4

NOTES: 1. MATERIAL:

HOUSING: THERMOPLASTIC WITH GLASS FIBER, UL94V-0, COLOR IN BLACK.
 LATCHES: THERMOPLASTIC WITH GLASS FIBER, UL94 HB, COLOR IN BLACK.
 CONTACTS: COPPER ALLOY.
 BOARDLOCKS: COPPER ALLOY.

2. FINISH:

CONTACTS: GOLD PLATING ON CONTACT AREA,
 100u"MIN. TIN/LEAD OR 60u" MATTE TIN (LEAD FREE OPTION) PLATING ON SOLDERTAILS,
 50u"MIN. NICKEL UNDERPLATING OVER ALL.
 BOARDLOCKS : 100u" TIN/LEAD OR MATTE TIN (LEAD FREE OPTION) PLATING ON SOLDERTAILS,
 50u"MIN. NICKEL UNDERPLATING OVER ALL.

3. WARNING: THE MAXIMUM ALLOWABLE ANGLE TO WITHDRAWAL THE DAUGHTER CARD FROM RETAINER BY 20 DEGREE.
 4. DURABILITY: 50 CYCLES.

5. RoHS COMPATIBLE PRODUCT SPECIFICATIONS
 a. PLATING: "LF" MEANS THE PRODUCT IS LEAD FREE, 2.5um min. MATTE PURE TIN OVER 1.27um MIN. NICKEL UNDERPLATE.

b. MANUFACTURING PROCESS COMPATIBILITY: THE HOUSING WILL WITHSTAND EXPOSURE TO 260C±5C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.60MM THICK CIRCUIT BOARD.

PRODUCT NUMBER CODE

10046742 -x x x x x x LF

APPLICATIONS
 BLANK - LEAD CONTAIN FOR PLATING OPTIONS 3,4,5
 LF - LEAD FREE FOR PLATING OPTIONS 0,1,2

HOUSING COLOR OPTIONS
 1-BLACK FOR BASE & RM
 2-BLACK FOR BASE & WHITE FOR RM
 3-BLUE (287U) FOR BASE & RM
 4-BLUE (297U) FOR BASE & RM

PEGS OPTIONS

1-METAL & PLASTIC COMPOUND

TERMINAL PLATING OPTIONS

0-50u" Ni: UNDERPLATE
 30u" Au CONTACT AREA
 100u" TIN TAIL AREA
 1-50u" Ni: UNDERPLATE
 15u" Au CONTACT AREA
 100u" TIN TAIL AREA
 2-50u" Ni: UNDERPLATE
 GOLD FLASH CONTACT AREA
 100u" TIN TAIL AREA
 3-50u" Ni: UNDERPLATE
 30u" Au CONTACT AREA
 100u" TIN/LEAD TAIL AREA
 4-50u" Ni: UNDERPLATE
 15u" Au CONTACT AREA
 100u" TIN/LEAD TAIL AREA
 5-50u" Ni: UNDERPLATE
 GOLD FLASH CONTACT AREA
 100u" TIN/LEAD TAIL AREA

PACKAGING OPTIONS
 T-TRAY PACKAGING

POS OPTIONS
 3-164

TAIL LENGTH OPTION (DIM A)
 1- 3.10MM
 2- 2.30MM

mat'l. code	ecn no	dr	date	linear	tolerances unless otherwise specified	projection	customer COPY	title	product family	code
E				.XX ± 0.25	.X ± 0.38	MM	FCI	PCI-E INTEGRATED TYPE CARD EDGE ASSY	EDGE CARD	TWIN
				.XXX ± 0.10	0 ± 2°					3 of
				dr JASON HSU 2/23/05	engr JASON HSU 2/23/05	MM				
				chr STERLING LIN 2/23/05	pppl HC LIOU 2/23/05	1:1				
sheet	revision									
index	sheet									

1 | 2

3

4

ACAD

code
22526